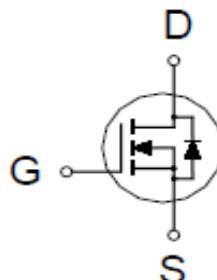
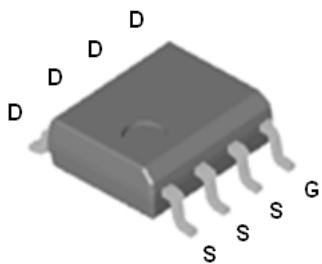


PV600BA

N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30V	10.8mΩ @ $V_{GS} = 10V$	10A



SOP-8

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A = 25^\circ C$	I_D	10	A
			8	
Pulsed Drain Current ¹		I_{DM}	40	
Avalanche Current		I_{AS}	17.6	
Avalanche Energy	$L = 0.1mH$	E_{AS}	15.5	mJ
Power Dissipation	$T_A = 25^\circ C$	P_D	1.95	W
			1.25	
Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		64	°C / W
Junction-to-Case	$R_{\theta JC}$		25	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$.

PV600BA N-Channel Enhancement Mode MOSFET

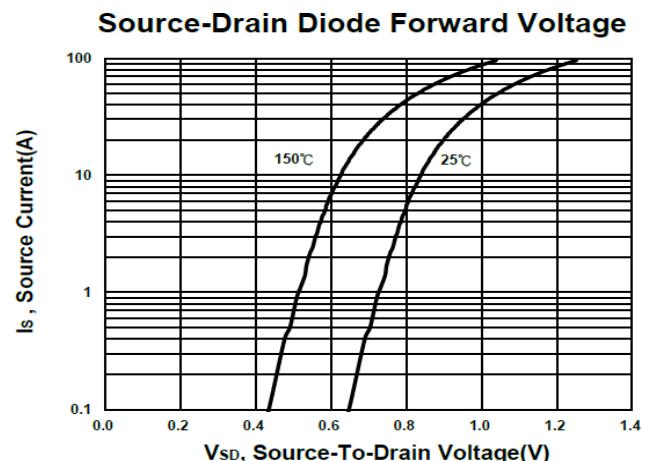
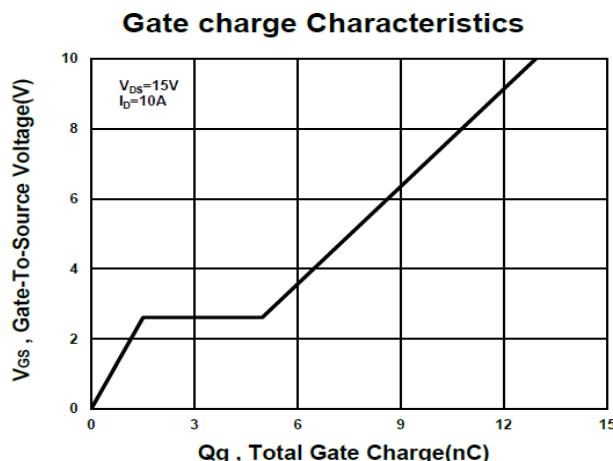
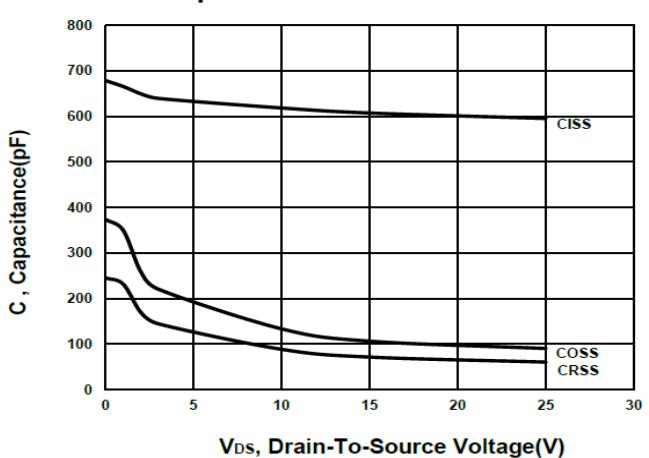
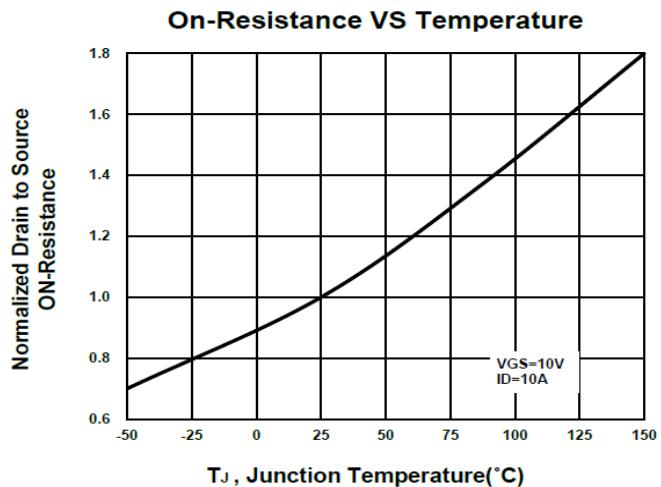
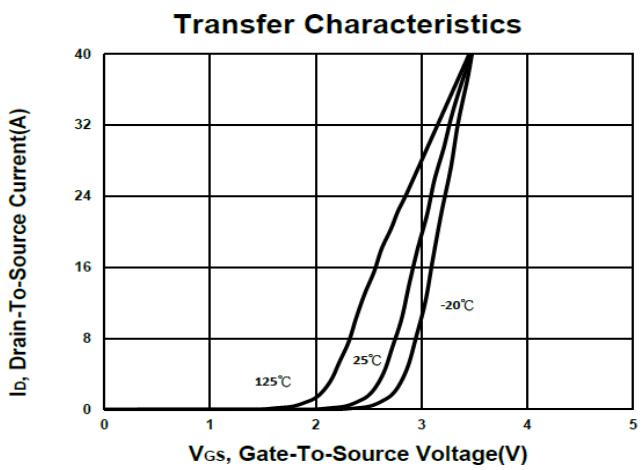
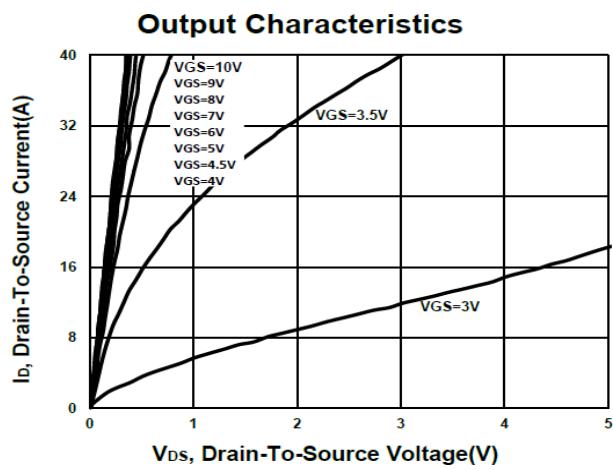
ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.3	1.7	2.3	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$		10.6	15	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$		8.3	10.8	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 10\text{A}$		40		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1\text{MHz}$		616		pF
Output Capacitance	C_{oss}			108		
Reverse Transfer Capacitance	C_{rss}			76		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		2.8		Ω
Total Gate Charge ²	$Q_g(V_{\text{GS}}=10\text{V})$	$V_{\text{DS}} = 15\text{V}, I_D = 10\text{A}$		13.8		nC
	$Q_g(V_{\text{GS}}=4.5\text{V})$			7.2		
Gate-Source Charge ²	Q_{gs}			1.7		
Gate-Drain Charge ²	Q_{gd}			3.9		
Turn-On Delay Time ²	$t_{\text{d(on)}}$	$V_{\text{DS}} = 15\text{V}, I_D \geq 10\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		15		nS
Rise Time ²	t_r			41		
Turn-Off Delay Time ²	$t_{\text{d(off)}}$			50		
Fall Time ²	t_f			27		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current	I_S				1.8	A
Forward Voltage ¹	V_{SD}	$I_F = 10\text{A}, V_{\text{GS}} = 0\text{V}$			1.1	V
Diode Reverse Recovery Time	t_{rr}	$I_F = 10\text{A}, dI/dt = 100\text{A}/\mu\text{s}$		12		nS
Diode Reverse Recovery Charge	Q_{rr}			3		nC

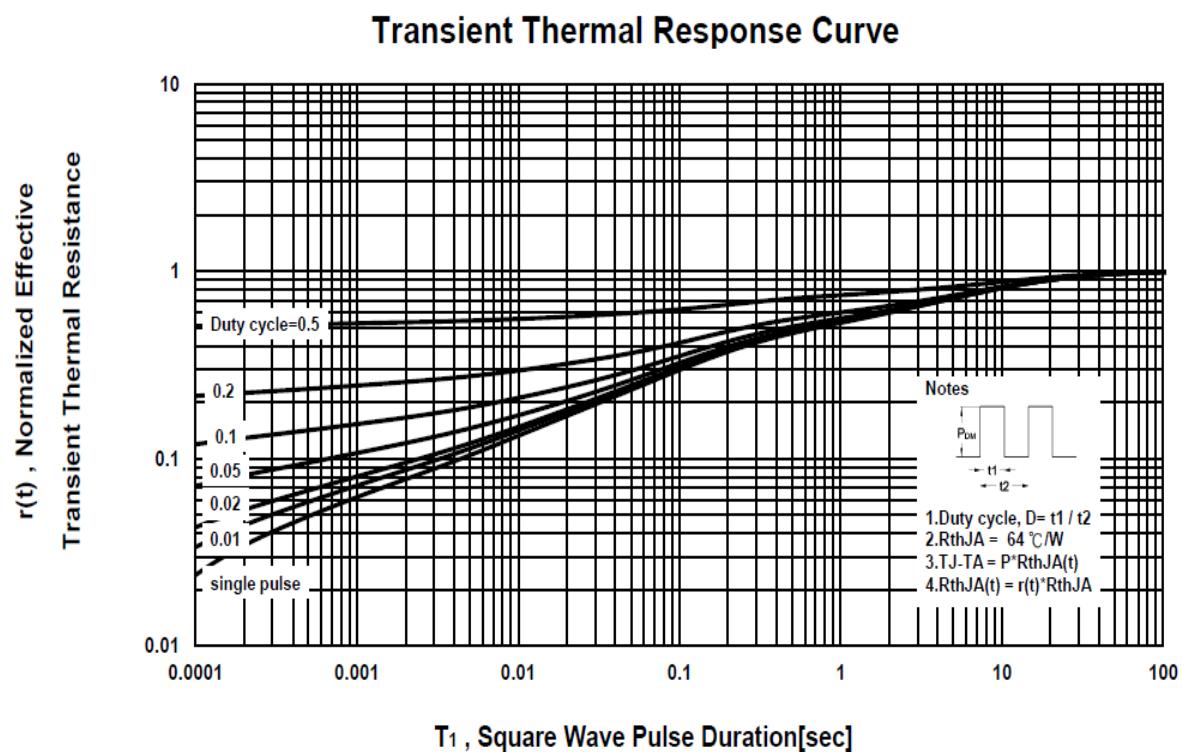
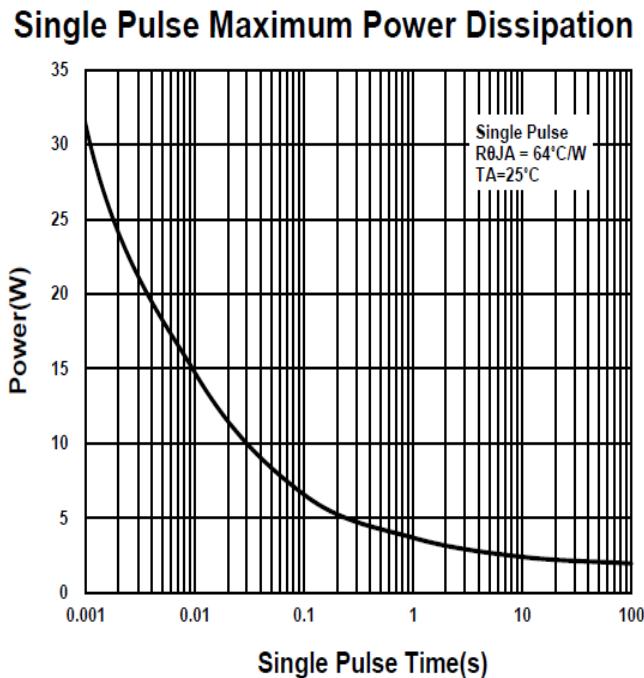
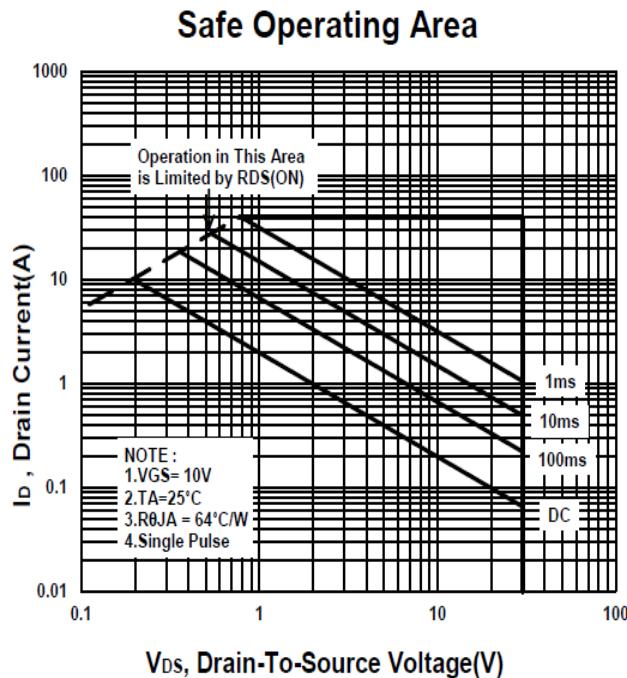
¹Pulse test : Pulse Width $\leq 300\text{ }\mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

PV600BA N-Channel Enhancement Mode MOSFET



PV600BA N-Channel Enhancement Mode MOSFET



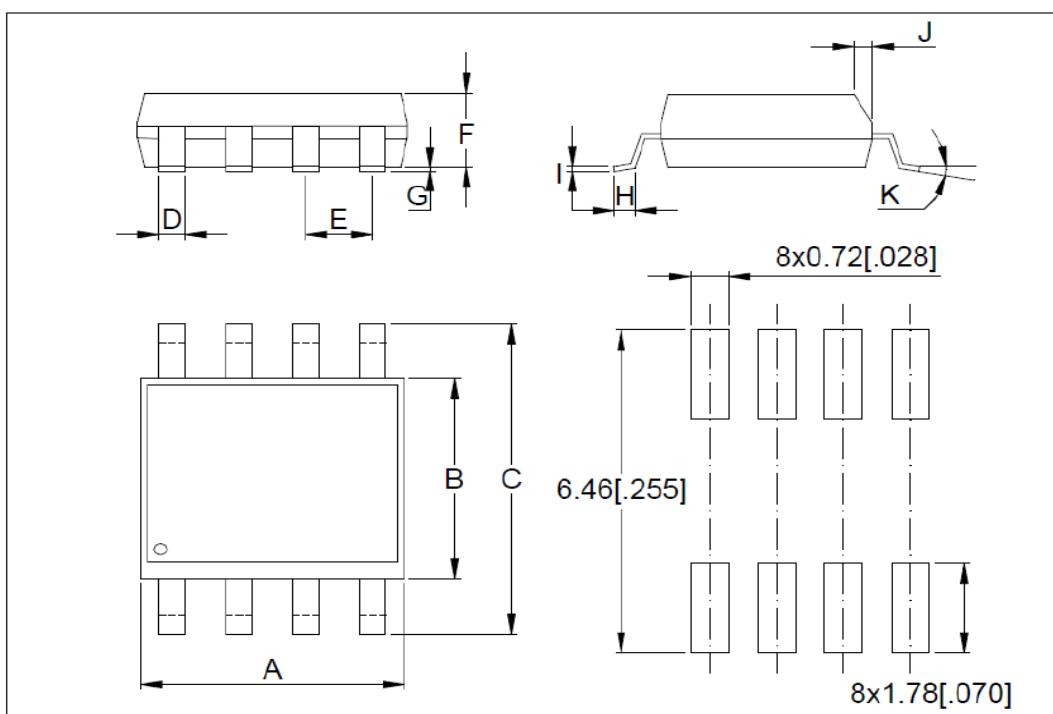
PV600BA

N-Channel Enhancement Mode MOSFET

Package Dimension

SOP-8 MECHANICAL DATA

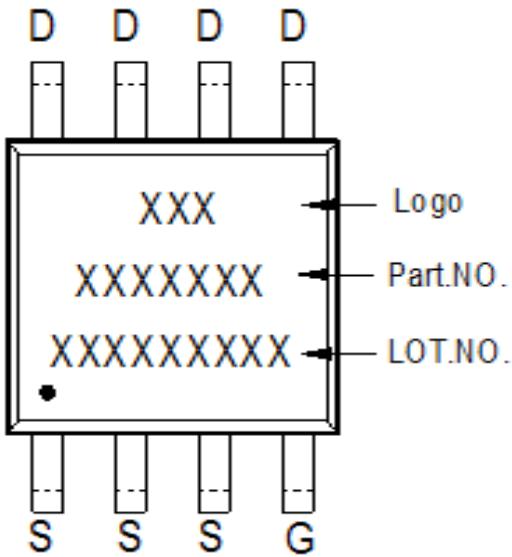
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	H	0.4	0.6	0.93
B	3.8	3.9	4.0	I	0.19	0.21	0.25
C	5.79	6.0	6.2	J	0.25	0.375	0.5
D	0.33	0.4	0.51	K	0°	3°	18°
E	1.25	1.27	1.29				
F	1.1	1.3	1.65				
G	0.05	0.15	0.25				



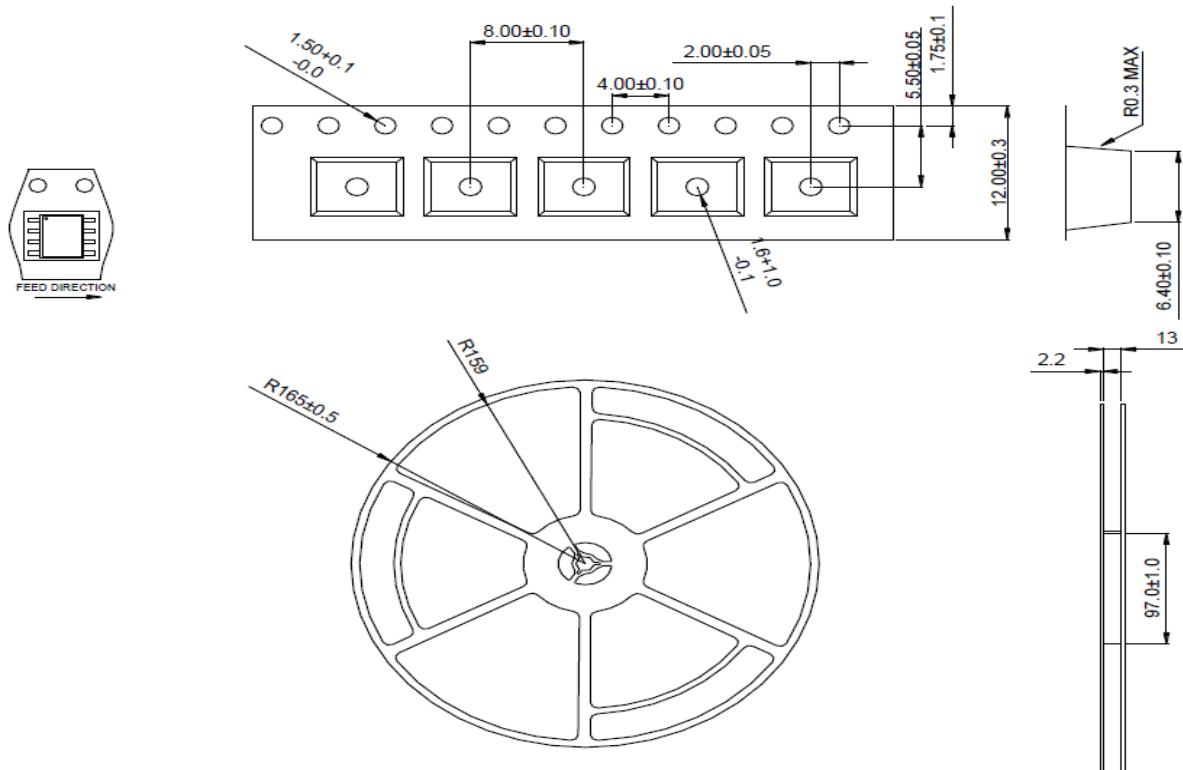
PV600BA

N-Channel Enhancement Mode MOSFET

A. Marking Information



B. Tape&Reel Information: 2500pcs/Reel



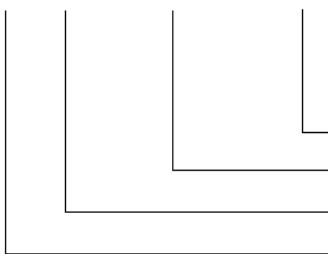
PV600BA

N-Channel Enhancement Mode MOSFET

C. Lot.No. & Date Code rule

1.LOT.NO.

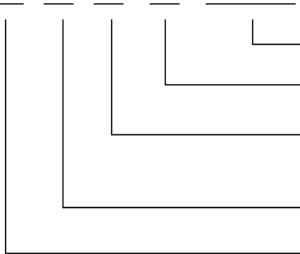
M N 15M21 03



- #8~9 Sub-lot No
- Order series no.
- Foundry site
- Assembly site

2.Date Code

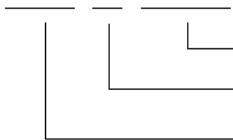
D Y M X XXX



- Order series no. & Sub-lot No
- Week
- M : Month (A:Jan , B:Feb , C:Mar ,D :Apr ,E:May ,F:Jun,G:Jul,H:Aug,I:Sep,J:Oct,K:Nov,L:Dec.)
- Y : Year (N : 2011, O : 2012 ...)
- Assembly site

3.Date Code (for Small package)

XX Y WW



- Week
- Y : Year (9: 2009,A : 2010, B : 2011 ...)
- Device Name

PV600BA N-Channel Enhancement Mode MOSFET

D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)
3	Great Power	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	Pb Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
12	Scan info	Device / Lot / D/C / QTY , Insert “ / ” between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least